

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KEI TANAKA	07/24/2014
TAKANOBU ROKUKA	07/24/2014
HITOSHI MORIYA	07/24/2014
SHIGERU MAHARA	07/23/2014
NORIAKI IWASAKI	07/23/2014
YOSHINORI MIURA	07/24/2014
KEI NAGABAYASHI	07/24/2014
YOSHIMASA ABE	07/24/2014
RECEIVING PARTY DATA	
Name:	SUMIDA CORPORATION
Street Address:	SUITENGU HOKUSHIN BUILDING, 1-39-5, NIHONBASHI, KAKIGARA-CHO
City:	CHUO-KU, TOKYO
State/Country:	JAPAN
Postal Code:	103-8589
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15648844
CORRESPONDENCE DATA	
Fax Number:	(860)286-0115
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	860-286-2929
Email:	usptopatentmail@cantorcolburn.com
Correspondent Name:	CANTOR COLBURN LLP
Address Line 1:	20 CHURCH STREET
Address Line 2:	22ND FLOOR
Address Line 4:	HARTFORD, CONNECTICUT 06103
ATTORNEY DOCKET NUMBER:	IWP0095USC
NAME OF SUBMITTER:	DANIEL P. LENT
SIGNATURE:	/Daniel P. Lent/

PATENT

DATE SIGNED:	07/13/2017
Total Attachments: 2 source=7V05229#page1.tif source=7V05229#page2.tif	

ASSIGNMENT

WHEREAS We, **Kei TANAKA, Takanobu ROKUKA, Hitoshi MORIYA, Shigeru MAHARA, Noriaki IWASAKI, Yoshinori MIURA, Kei NAGABAYASHI** and **Yoshimasa ABE** of **c/o Sumida Electric Co., Ltd., 31-1, Aza-Miyajima, Uematsu, Natori-city, Miyagi, 981-1226 Japan** (hereinafter referred to as "ASSIGNORS") have invented certain new and useful improvements in:

ANTENNA COIL COMPONENT, ANTENNA UNIT, AND METHOD OF MANUFACTURING THE ANTENNA COIL COMPONENT

which claims priority to **Japanese Application No. 2013-166256, filed August 9, 2013,** and **Japanese Application No. 2014-099486, filed May 13, 2014,** and for which I am about to file or have filed an application for Letters Patent of the United States;

AND WHEREAS, **SUMIDA CORPORATION** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of **Japan,** having a place of business at **Suitengu Hokushin Building, 1-39-5, Nihonbashi Kakigara-cho, Chuo-ku, Tokyo, 103-8589 Japan,** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications

when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: <u>2014. 7. 24</u>	<u>Kei TANAKA</u> L.S. Kei TANAKA
Date: <u>2014. 7. 24</u>	<u>Takanobu ROKUKA</u> L.S. Takanobu ROKUKA
Date: <u>2014. 7. 24</u>	<u>Hitoshi Moriya</u> L.S. Hitoshi MORIYA
Date: <u>2014. 7. 23</u>	<u>Shigeru MAHARA</u> L.S. Shigeru MAHARA
Date: <u>2014. 7. 23</u>	<u>Noriaki Iwasaki</u> L.S. Noriaki IWASAKI
Date: <u>2014. 7. 24</u>	<u>Yoshinori Miura</u> L.S. Yoshinori MIURA
Date: <u>2014. 7. 24</u>	<u>Kei Nagabayashi</u> L.S. Kei NAGABAYASHI
Date: <u>2014. 7. 24</u>	<u>Yoshimasa ABE</u> L.S. Yoshimasa ABE